INSIDE RESCHIP4EU

Edition 1 | April 2026

Powering Europe's next generation of chip talent

RESCHIP4EU

Reinforcing Skills in Chips Design for Europe

Co-funded by the European Union

WELCOME!

We are excited to launch this new space where we will share the latest news, achievements, events, and opportunities from the RESCHIP4EU community. In each edition, we will take you **behind the scenes of our work,** highlight key milestones, and keep you informed about **upcoming activities, learning opportunities, and developments in chip design, semiconductors, and embedded systems education** in Europe.

PROJECT PRESENTATION

I would put my chips on Europe; would you?

Challenge: Europe faces a significant shortage of skilled engineers in chip design and microelectronics

RESCHIP4EU response: strengthening higher education in embedded systems and intelligent chip design, helping build Europe's next generation of semiconductor engineers Semiconductors are at the core of Europe's digital and industrial future

- a double-degree Master's programme (120 ECTS) focused on Intelligent Chips and Systems
- training that spans the entire stack—from silicon and System-on-Chip design to smart embedded platforms
- a minor in Innovation and Entrepreneurship
- additional online modules in microelectronics and chip design for professionals.

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OUR CONSORTIUM

RESCHIP4EU is coordinated by 28DIGITAL and brings together 13 beneficiaries and 3 associated partners across 7 European countries, combining the strengths of leading universities, industry actors, and innovation experts to **build a strong and future-oriented European skills ecosystem in Intelligent Chips Systems (ICS) and chip design.** Find out who we are HERE.

WHAT OUR PARTNERS SAY ABOUT RESCHIP4EU

"Talent is the key to all of Europe's ambitions for the semiconductor industry."

Bernard Capraro,
Senior Manager, University Partnerships & Talent Initiative SEMI Europe

"To be an engineer in this industry, means constant thinking of innovation. It requires much more than technical skills: open mindset and team exchanges are the only way to make innovation progress fast"

Didier MARTIN,
Microcontrollers, Digital ICs and RF product Group, Central R&D – Methodology & Design Flow, STMicroelectronics

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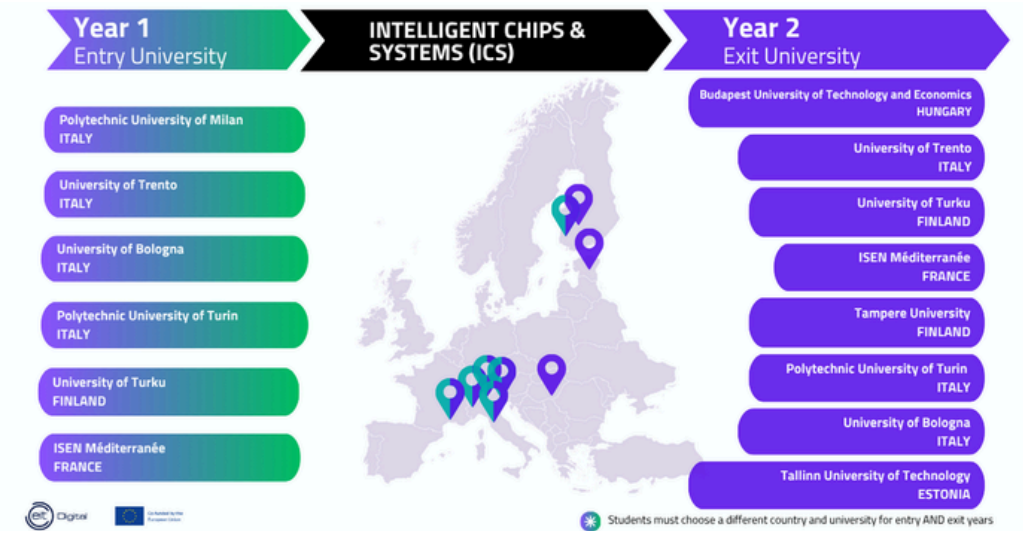
HOW DOES THE PROGRAMME WORK

Two countries, two universities, one shared learning journey. Students start at an **Entry University** in year one, continue at an **Exit University** in year two, and complete the experience with the **EIT Digital Summer School** in between. More than a mobility path, this is a chance to learn in different academic environments, connect with an international community, and build the kind of cross-border experience that today's semiconductor sector increasingly needs.



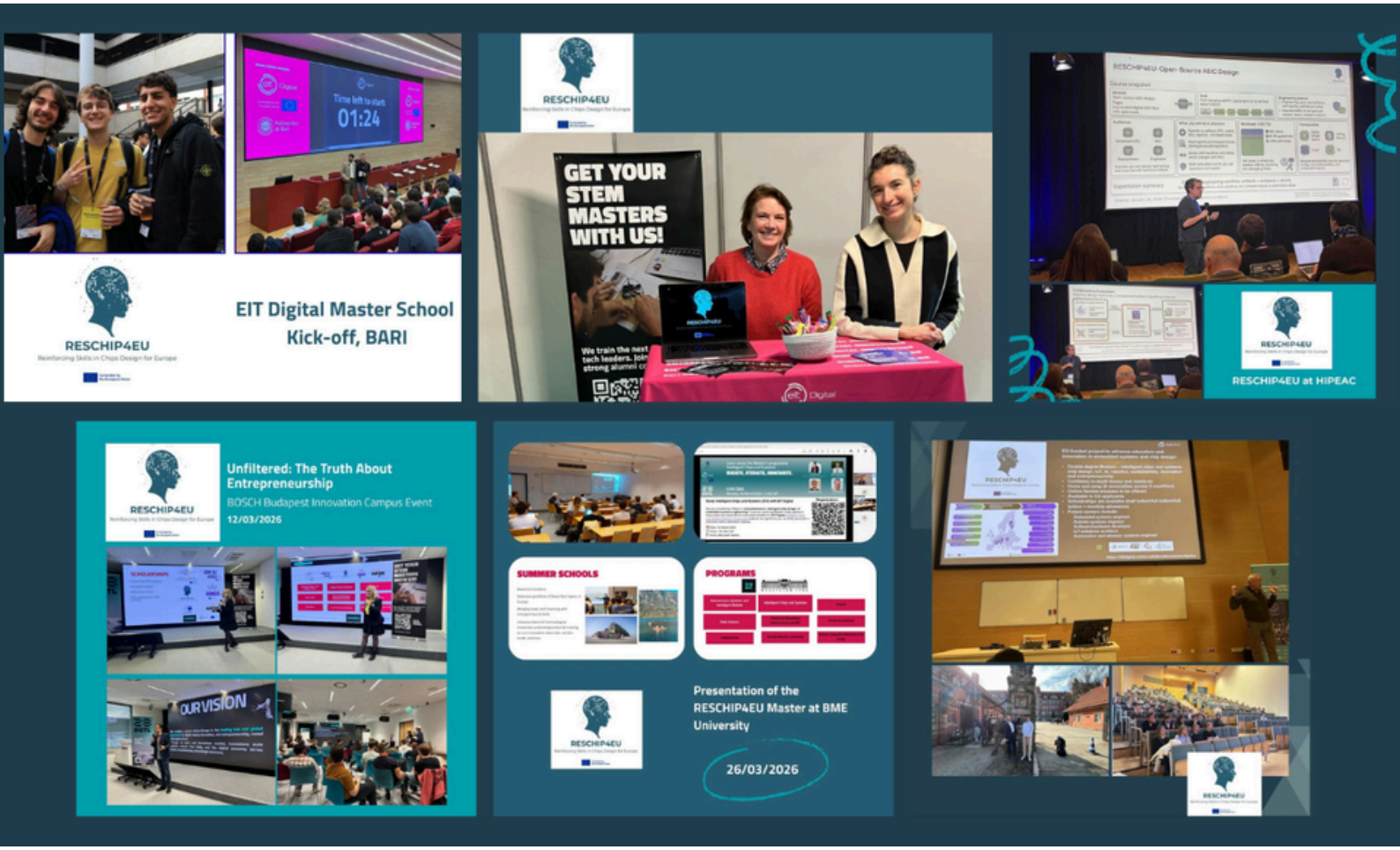
Want to build skills to design not only embedded systems but also chips in a flexible and combined manner? RESCHIP4EU has developed **11 self-standing learning modules** to meet the need for additional education for both professionals and university learners.

These modules fall into three main areas: **hardware design, embedded application design, and security and reliability.** They are offered through a single digital platform that combines self-paced online learning with selected live sessions, and learners can follow them either as stand-alone courses or as part of a specific area, with free access to all courses. Participants who complete the modules will also receive a certificate of completion.

EVENT HIGHLIGHTS

Since its launch, RESCHIP4EU has strengthened its visibility through a range of **outreach and promotional activities** within Europe. The programme was presented at several education fairs and student-oriented events, including L'Etudiant – Salon Informatique, Numérique, Cybersécurité, Data et IA in Paris, the EIT Digital Master School Kick-off in Bari.

Beyond these student-focused activities, **RESCHIP4EU was also featured in a wider set of ecosystem-oriented events,** including the HiPEAC Conference in Kraków, SEMI on Campus at GdańskUniversity of Technology, the information session at Budapest University of Technology and Economics (BME), and the entrepreneurship workshop Unfiltered: the Truth About Entrepreneurship – Turning Ideas into Action in Budapest.



SPOTLIGHT

Last November, Munich hosted **SEMICON Europa 2025, Europe's premier semiconductor trade fair,** bringing together policymakers, industry leaders, researchers, and educators. **RESCHIP4EU was also presented by SEMI Europe as a response to Europe's growing talent gap,** with the region facing a shortfall of nearly 11,000 semiconductor professionals every year by 2030 - gaps in labs, design teams, and future startups.

DROP-IN SESSIONS

RESCHIP4EU was also featured during **EIT Digital Master School drop-in sessions**, held at Politecnico di Torino, Politecnico di Milano and TalTech – Tallinn University of Technology. These sessions gave prospective students the opportunity to learn more about the programme, ask questions, and explore topics such as scholarships, curriculum structure, and student experience.

WEBINARS

RESCHIP4EU was further promoted through a recent **online information session**, Study Intelligent Chips and Systems (ICS) with EIT Digital Master School, featuring **program leads, professors, and industry experts** sharing insights into the ICS track, student experience, and career opportunities within the semiconductor ecosystem. The session attracted strong interest, with 308 views of the registration page, 60 registrations, and 31 attendees joining us live.

The European Union is preparing a **Chips Act 2.0** to build on the first Chips Act adopted in 2023, to expand support for semiconductor research, innovation, and industrial deployment in Europe.

At the same time, the **FAMES pilot line** at CEA-Leti in Grenoble, backed by €830 million, has become the first of five Chips Act pilot lines to become operational, focusing on FD-SOI technology, which enables chips to run on 30–40% less power in areas such as edge computing, automotive, IoT, 5G/6G, defence, and medical devices.

RESCHIP4EU is launching a new article series led by project partners to open up key topics in microelectronics, chip design, and digital skills to a wider audience. Rather than scientific publications, the series focuses on **accessible, insight-driven pieces that reflect the perspectives of partners working within education, industry, and innovation.**

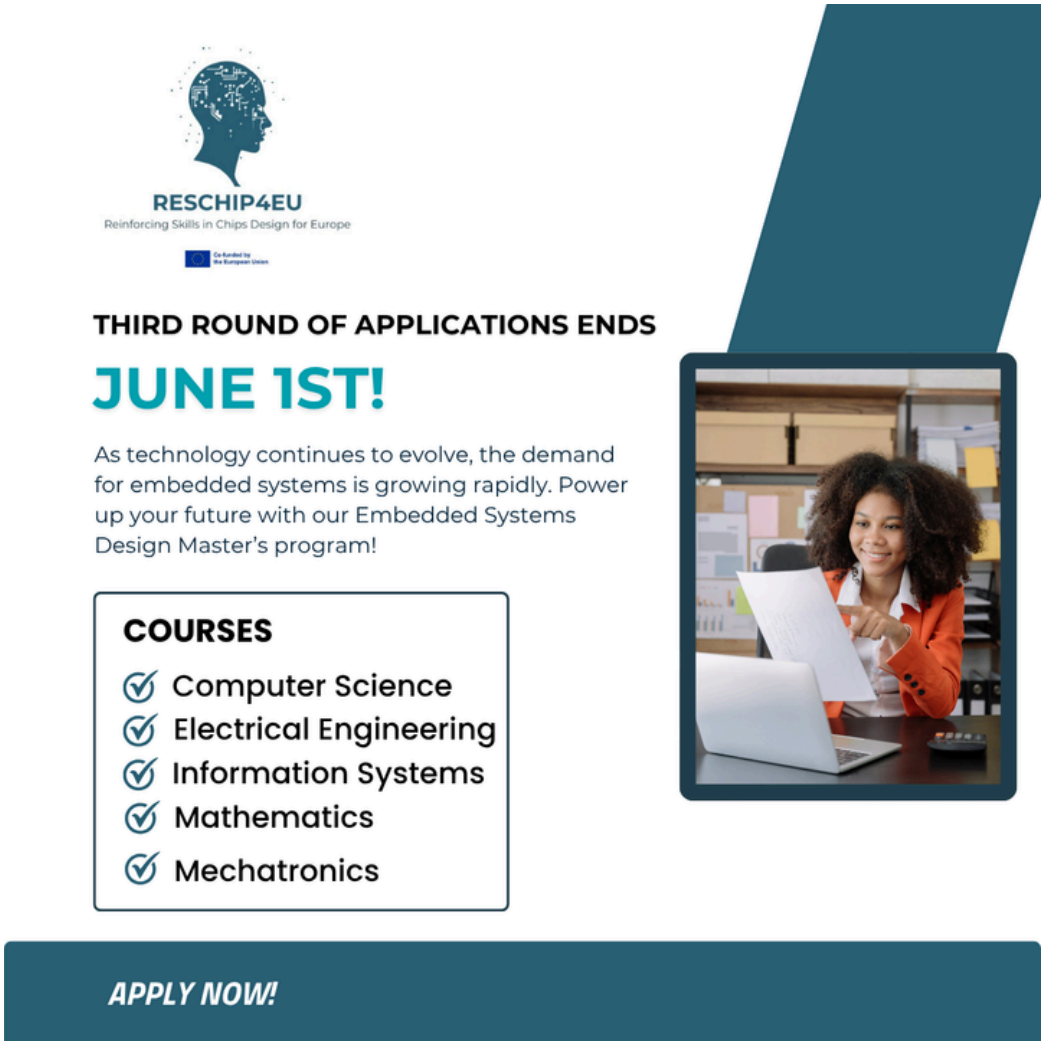
The first article, published by JA Europe, "**Who Builds Europe's Digital Future Matters,"** explores the growing AI skills gap and the need to broaden participation in digital and semiconductor careers, with additional contributions from partners to follow in the coming month.

✨**Ready to turn your interest in microelectronics into a career?**

Applications for the third round remain open until **1 June**, inviting future chip designers, engineers, and innovators to take the next step.

And the outcomes show the value of that choice. Our **results** speak for themselves: 92% of our alumni are employed after graduation, with 83% securing their first role within just three months. Don't wait, **apply** now and join the next generation building Europe's semiconductor future.

Subscribe to our newsletter and become part of the RESCHIP4EU community for the latest news, events, and opportunities.



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Thank You